

WHAT IS CLAIMED IS:

1. A multilayer wired board constituting at least part of a electrical circuit board in which a plurality of wired boards are stacked so as to face their wired surfaces each 5 other, wherein:

electrical connection parts between said multilayer wired boards are connected through an elastic conductive material part adhered to one of said wired boards; and

10 at least part of a peripheral edge portion of said elastic conductive material part is adhered by a double-sided adhesive material part to seal said plurality of multilayer wired boards.

2. The multilayer wired board according to claim 1, wherein 15 said elastic conductive material part is formed in a convex shape, the bottom of said elastic conductive material part is adhered to one of said wired boards and the top of said elastic conductive material part is adhered to an electrical connection part of other side of said wired board, whereby 20 electrical connection is established.

3. The multilayer wired board according to claim 1, wherein 25 said elastic conductive material part is formed in a convex shape and the height from the bottom to the top of said elastic conductive board is set to 200 - 400 μ m.

4. A method of a multilayer wired board constituting at least part of a electrical circuit board in which a plurality of wired boards are stacked so as to face their wired surfaces 30 each other, comprising the steps of:

adhering an elastic conductive material part to an

electric connection part of one of said wired boards;

forming an opening in a double-sided adhesive material part so as to surround at least part of the peripheral edge of said elastic conductive material part;

5 adhering said double-sided adhesive material part to a wired board adhered said elastic conductive material part or other wired board whose wired surface to be faced to said wired surface; and

 adhering said both wired boards together by said

10 double-sided adhesive material part under the state in which the top of said elastic conductive material part is contacted to the electrical connection part of said other wired board whose wired surface to be faced to said wired surface.

15 5. The method of a multilayer wired board according to claim 4, wherein said elastic conductive material part is formed in a convex shape.

20 6. The method of a multilayer wired board according to claim 4, wherein said elastic conductive material part is formed in a convex shape and the height from the bottom to the top of said elastic conductive board is set to 200 - 400 μ m.

25 7. A touch panel comprising the configuration such that a light transmission first board having a light transmission conductive layer formed as a predetermined pattern thereon and a light transmission second board made of a flexible material having a light transmission conductive layer thereon is placed opposite to said first board with a predetermined distance, wherein:

30 electrical connection parts between said first board

and said second board are connected through an elastic conductive material part adhered only to said first board, at least part of a peripheral edge portion of said elastic conductive material part is adhered by a double-sided adhesive 5 material part to seal said first board and said second board.

8. The touch panel according to claim 7, wherein said elastic conductive material part is formed in a convex shape, the bottom of said elastic conductive material part is adhered to said 10 first board and the top of said elastic conductive material part is adhered to an electrical connection part of said second board, whereby electrical connection is established.

9. The touch panel according to claim 7, wherein said elastic 15 conductive material part is formed in a convex shape and the height from the bottom to the top of said elastic conductive board is set to 200 - 400 μ m.

10. A method of a touch panel comprising the configuration 20 such that a light transmission first board having a light transmission conductive layer formed as a predetermined pattern thereon and a light transmission second board made of a flexible material having a light transmission conductive layer thereon is placed opposite to said first board with a 25 predetermined distance, comprising the steps of:

adhering an elastic conductive material part to an electric connection part of said first board;

forming an opening in a double-sided adhesive material part so as to surround at least part of the peripheral edge 30 of said elastic conductive material part;

adhering said double-sided adhesive material part to

said first board and said second; and

 adhering said both first and second board together by
 said double-sided adhesive material part under the state in
 which the top of said elastic conductive material part is
5 contacted to the electrical connection part of said second.

11. The method of a touch panel according to claim 10, wherein
 said elastic conductive material part is formed in a convex
 shape.

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12. The method of a touch panel according to claim 10, wherein
 said elastic conductive material part is formed in a convex
 shape and the height from the bottom to the top of said elastic
 conductive board is set to 200 - 400 μ m.

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